

CLAIMS

1. (CANCELLED) An apparatus, comprising:

a first disc member;

a main body, in communication with said first disc member; and

a second disc member;

wherein said main body contains at least one environmental sensor.

2. (NEW) A monitoring device for silicon wafer transfer pods, comprising:

a top part;

a cylinder in communication with said top part;

a bottom part in communication with said cylinder;

a control unit in communication with said cylinder; and

a wireless link in communication with said control unit.

3. (NEW) The monitoring device of claim 2 wherein said top part and said bottom part are the same circular shape as the silicon wafer transfer pods.

4. (NEW) The monitoring device of claim 2 wherein said top part and said bottom part are configured to fit inside the silicon wafer transfer pods.

5. (NEW) The monitoring device of claim 2 wherein said top part, said bottom part and said cylinder accompany silicon wafers in the transfer pods throughout a manufacturing process.

6. (NEW) The monitoring device of claim 2 wherein said cylinder is configured to draw in air to a conventional particle detector.

7. (NEW) The monitoring device of claim 2 wherein said control unit is configured to detect any change in the environment of the silicon wafer transfer pods.
8. (NEW) The monitoring device of claim 2 wherein said wireless link is configured to display warning, flow, or failure status lights when there is a change in the environment of the silicon wafer transfer pods.
9. (NEW) The monitoring device of claim 2 wherein said cylinder houses sensor equipment.
10. (NEW) A monitoring device for silicon wafer transfer pods, comprising:
 - two discs;
 - at least one sample tube between said discs;
 - wherein said discs and said at least one sample tube are configured to fit inside a silicon wafer transport pod for monitoring particles.